A superconducting metallic glass transition-edge sensor (MGTES) and a method for fabricating the MGTES are provided. A single-layer superconducting amorphous metal alloy is deposited on a substrate. The single-layer superconducting amorphous metal alloy is an absorber for the MGTES and is electrically connected to a circuit configured for readout and biasing to sense electromagnetic radiation.
References Cited

OTHER PUBLICATIONS


* cited by examiner
FIG. 2
(PRIOR ART)
FIG. 3

Si-N Support 305

Absorber/MGTES 302

Superconducting Leads/bond pads on Si-N Support 306

SQUID 308

FIG. 4

Amorphous Zr$_{75}$Rh$_{25}$

$T_{co} = 4.562$

$R(T)/R_{o}$

(a)

$H_{c2}(T)$ KG

(b)

$4.55$ $4.56$ $4.57$ $4.58$

$T (°K)$

$0.0$ $0.5$ $1.0$

$t = T/T_{co}$

Maki Theory

Linear Extrapolation
FIG. 5

Temperature (K) vs. Resistivity ($\rho$)
SUPERCONDUCTING METALLIC GLASS TRANSITION-EDGE-SENSORS

CROSS-REFERENCE TO RELATED APPLICATIONS

This application claims the benefit under 35 U.S.C. Section 119(e) of the following co-pending and commonly-assigned U.S. provisional patent application(s), which is/are incorporated by reference herein:


STATEMENT REGARDING FEDERALLY SPONSORED RESEARCH AND DEVELOPMENT

The invention described herein was made in the performance of work under NASA Contract Number NASI-1407 and is subject to the provisions of Public Law 96-517 (35 USC 202) in which the Contractor has elected to retain title.

BACKGROUND OF THE INVENTION

1. Field of the Invention

The present invention relates generally to imaging, and in particular, to a method, apparatus, and article of manufacture for fabricating and using a metallic glass transition-edge-sensor (MGTES) device.

2. Description of the Related Art

(Note: This application references a number of different publications as indicated throughout the specification by reference numbers enclosed in brackets, e.g., [x]. A list of these different publications ordered according to these reference numbers can be found below in the section entitled “References.” Each of these publications is incorporated by reference herein.)

Actively cooled, direct radiation detectors, which exhibit improved image and energy resolution in the infrared (IR) and x-ray wavelength regions, are a next-generation technology for advanced imaging, for both terrestrial and space applications. In this regard, NASA’s Science Mission Directorate (SMD) is driven in part by the motivation for understanding the content and evolution of matter in the known universe. To support these goals, a broad spectrum of missions are planned to conduct measurements at submillimeter and far-infrared (FIR) wavelengths; e.g., the NASA proposed Background-Limited far-IR/Submillimeter Spectrograph (BLISS) and the Spica A FAR Infrared Instrument (SAFARI) instruments for Japan’s Space Infrared Telescope for Cosmology and Astrophysics (SPICA) mission. SPICA requires actively cooled, direct radiation detectors, with very high sensitivity. Potential terrestrial applications for actively cooled, direct radiation detectors arrays are: 1) x-ray detectors for medical imaging; 2) chemical analysis for materials science (Scanning-electron-microscopy/Dispersive Spectroscopy) at x-ray wavelengths; and 3) radiation detectors for nuclear forensics (e.g., Alpha-particle and gamma-ray detection).

Membrane-isolated superconducting transition-edge-sensor (TES) arrays are a leading sensor technology for such space applications (see [1]-[3]). To meet application requirements, the detectors must be formatted into large-scale high pixel density arrays, which will be read using superconducting quantum interference detector (SQUID) Multiplexer (MUX) technology. Detector arrays that use the current baseline transition edge sensor technology, i.e., state-of-the-art (SOA) TES arrays, do not exhibit the performance requirements of the BLISS instrument. The BLISS instrument requires detectors with the following performance metrics: 1) fast response time τ (<100 ms); 2) high pixel density arrays (at least 10^6 pixels); 3) TES films must exhibit stable T_c<100 mK; 4) must perform over a broad wavelength range 35 mm-433 mm; 5) low detector noise equivalent power (NEP) of the order NEP<1x10^-10 W/Hz; and 6) low 1/f noise level at low frequencies, i.e., below 10 Hz.

TES-based microcalorimeter arrays are being developed for the mission listed above, as well as the NASA Beyond Einstein Program Constellation-X Observatory (Con-X), for measurements of x-ray spectra). SOA TES devices detect radiation by precisely measuring the temperature rise associated with the absorption of a photon, which raises the TES temperature. The temperature increase is detected by a superconducting thermistor, which is voltage-biased 10-20% into the superconducting transition curve at T=T_c. The superconducting thermistors in SOA TES devices are typically based on: 1) elemental superconducting films; e.g., Titanium (Ti, T_c=56.5 K) or Iridium (Ir, T_c=130 mK); and 2) proximity effect elemental metallic bilayer design: e.g., Mo/Au. FIGS. 1A and 1B illustrate an ordinary bilayer Mo/Au (Molybdenum/Gold) TES (FIG. 1A) and TES with stripes (FIG. 1B) (140 microns on a side, stripes spaced every 15 µm) of the prior art. In the single-layer elemental TES designs, the superconducting transition temperature T_c cannot be controlled, and is well above the desired operating temperature (~50 mK) for space applications. The bilayer TES device functions as a single superconducting element via the proximity effect, and the superconducting transition temperature, T_c, is controlled by the thickness of the superconductive film element. However, this TES device architecture has inherent problems, which are manifest in fabrication difficulties, control of the superconducting transition temperature, T_c, and an excess noise equivalent power spectrum.

In other words, while the techniques used to fabricate SOA TES single-layer elemental and bilayer designs are well developed, the TES device architecture exhibits a variety of problems: 1) device fabrication is difficult to control, resulting in variable superconducting transition temperature, T_c, from element to element; 2) broadened transition width, ΔT_c~2-30 mK; and 3) SOA TES devices exhibit an excess noise equivalent power spectrum (NEP) (see [4]-[5]).

SOA TES devices based on the bi-layer design are designed for operation at ~50 mK, and the individual TES films must exhibit similar T_c values for good performance. In SOA TES devices, the T_c values are difficult to control because these devices are fabricated using thin-film synthesis techniques based on geometry. Achieving the control necessary to fabricate large arrays is technically challenging, as the T_c is a sensitive function of the properties of both layers, as well as the interface transparency. In Mo/Au proximity effect bilayer TES designs, the lack of control of the residual resistance ratio (RRR) for as-sputtered Au films impacts the T_c value, and post-annealing to improve the RRR contribute to un-controlled changes in T_c.

The e-beam deposition techniques used to fabricate bilayer TES devices are also manifest with challenges. Typically, Mo/Au films are e-beam deposited onto an LSN (low-stress silicon nitride) substrate maintained at 600° C; the high substrate temperature is used to compensate for thermal expansion coefficient mismatch between the metal film and substrate. The remaining residual stress in these Mo-films is of the order 400 to 600 MPa (Megapascals). In these films, the residual stress shifted the superconducting transition temperature T_c by as much as 50 mK.
SOA single-layer elemental design TES detectors; e.g., based on Ti or Ir, typically exhibit an excess noise-equivalent-power (NEP), which is 2× larger (or greater) than that predicted by theory. SOA bilayer design TES detectors typically exhibit an NEP which is 4-10× greater than that predicted by theory. FIG. 2 illustrates excess noise in bilayer TES compared to the calculated Johnson noise of the TES and shunt resistor in the prior art. The source of this noise is unknown. Resolution of the excess noise is a global challenge for everyone in the field.

In the SOA designs, there are factors intrinsic to their design, which may limit the reduction of the excess noise spectrum to acceptable levels. For example, in Mo/Au proximity effect bilayer TES designs, the residual stress state in the bilayers has ramifications on the excess noise exhibited by these films. Local fluctuations in the film stress state, on spatial length scales of the order of the superconducting coherence length ξ can increase quasiparticle carrier scattering in the metallic layer, which can introduce additional noise. Defects present in the elemental crystalline films (e.g., grain boundaries and dislocations) contribute to an increase in quasiparticle charge carrier scattering at low temperatures, thereby increasing the noise levels observed. Interlayer quasiparticle carrier scattering in metallic bilayers will also introduce additional noise.

In addition to the technical challenges outlined above, another issue that limits the application of TES devices for terrestrial applications is the low TES operating temperature, Tao ~100 mK. To actively cool TES arrays to this temperature range, complex and costly cryogenic cooling methods (e.g., dilution refrigerators) are required. A TES technology that would enable operation at 0.3 K or higher, would be very desirable, as this temperature can be achieved using closed-cycle cryogenic systems using 3He or the newer adiabatic demagnetization refrigerator (ADR) system (e.g., a continuous adiabatic demagnetization refrigerator (ADR with 4-stages), a He3/He4 dilution refrigerator, or a cryogenic cooling system that uses liquid 4He).

The performance limiting difficulties associated with the SOA TES devices are:

- Tc controlled only by superconducting proximity effect in metallic bilayer design and for these ultra-thin films the substrate surface roughness broadens the transition; therefore Tc value is difficult to control;
- Energy resolution limited by low logarithmic sensitivity factor (α) values, manifest by large transition widths, ∆Tc;
- Large excess noise values at high frequencies [1-20 kHz] (up to 20 times theoretical expectations), correspondingly reduces the high-frequency sensitivity;
- Sources of large excess noise are unknown;
- Fabrication techniques introduce wide variability in TES performance values;
- SOA TES design itself introduces unavoidable extrinsic sources of excess noise; and
- Expensive cryogenic technology required to achieve cooling to ~100 mK.

SUMMARY OF THE INVENTION

As described above, prior art TES detectors include many limitations including:

- Tc value difficult to manage;
- Large excess high-frequency noise (often 2-10 times theoretical expectation) of unknown origin;
- Complex fabrication process; difficult to reproduce for large arrays; and
- Fabrication process introduces large residual stresses in bilayer films.

Embodiments of the invention provide a new type of transition edge sensor that will meet the requirements for many terrestrial (e.g., spectroscopy) and space-based sensing applications in the IR and X-ray wavelength regions. The novel devices are based on single-layer thin-films of superconducting amorphous metal alloys—i.e., metallic glasses. Changes in chemical composition are used to control the Tc in amorphous metal alloys, in thin-film form. Superconducting metallic glass forming alloys with Tc values as high as 7.6 K have been reported (see [6]-[7]), and a number of systems exhibit Tc’s near 300 mK (e.g., Zr40Cu60) (see [8]). In addition, superconducting metallic glasses typically exhibit very narrow transition widths ∆Tc ~0.1-10 mK. For example, Johnson et al report that a splat-quenched Zr52Rh48 metallic glass foil (45 μm thick) exhibits a superconducting transition Tc ~4.562 K, and a transition width, ∆Tc ~7 mK, defined by the 10% and 90% points on the resistive transition curve (see [6]-[7]). Therefore MGTES devices in accordance with embodiments of the invention can be operated at higher temperatures than conventional TES devices. Temperatures in this range are achieved using closed-cycle cryogenic systems that use 4He, resulting in an immediate decrease in overall operating cost for this type of cryogenically cooled detector array. In addition, the active element of MGTES device embodiments may be comprised of a single-layer alloy film, greatly simplifying the fabrication methodology used to fabricate a large array of MGTES devices. Further, intrinsic features associated with the disorders alloyed used in MGTES device embodiments contribute to a significant reduction in the NEP values, and with an improved energy resolution. MGTES devices will be subject to lower 1/f noise values due to their narrow superconducting transition temperature widths, which will minimize the bias-induced noise. All of these benefits extend to terrestrial applications operating at higher temperatures (T>100 mK).

BRIEF DESCRIPTION OF THE DRAWINGS

Referring now to the drawings in which like reference numbers represent corresponding parts throughout:

FIGS IA and IB illustrate an ordinary Mo/Au (Molybdenum/Gold) TES (FIG. 1A), TES with stripes (FIG. 1B) (140 microns on a side, stripes spaced every 15 μm) and grating-style absorber for Far-Infrared Radiation Far-IR or Sub-mm Spectroscopy (FIG. 1C) of the prior art;

FIG. 2 illustrates excess noise in bilayer TES compared to the calculated Johnson noise of the TES and shunt resistor in the prior art;

FIG. 3 illustrates a schematic of a MGTES device architecture in accordance with one or more embodiments of the invention;

FIG. 4 shows the superconducting transition observed in an amorphous Zr42Rh48 (At. %) splat-quenched foil in accordance with one or more embodiments of the invention;

FIG. 5 illustrates the temperature dependence of resistivity curves for: A) crystalline metals, B) weakly-scattering metallic glasses, and C) strongly-scattering metallic glasses in accordance with one or more embodiments of the invention;

FIG. 6 illustrates a mushroom-type absorber structure in accordance with one or more embodiments of the invention;

FIG. 7 illustrates four TES sensors on a SiN thermally isolated island structure in accordance with one or more embodiments of the invention; and
FIG. 8 illustrates distributed antenna-coupled small-volume arrays in accordance with one or more embodiments of the invention.

DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS

In the following description, reference is made to the accompanying drawings which form a part hereof, and which is shown, by way of illustration, several embodiments of the present invention. It is understood that other embodiments may be utilized and structural changes may be made without departing from the scope of the present invention.

Superconducting metallic glasses exhibit a number of desirable properties for applications of embodiments of the invention, and will exceed the performance of the SOA for each TES figure of merit:

- Improved energy resolution;
- Lower excess noise;
- Amorphous alloy may be a self-absorber of radiation (with 4d and 5d transition metal additions to alloy(s));
- Precisely controlled superconducting transition temperature, $T_c$;
- Simplified detector architecture; and
- Mechanically & chemically robust design.

Some of these advantages are detailed in Table 1:

<table>
<thead>
<tr>
<th>TES Figure of Merit</th>
<th>SOA</th>
<th>MGTES (Superconducting amorphous metal thin film)</th>
<th>Improvement MGTES vs. SOA</th>
</tr>
</thead>
<tbody>
<tr>
<td>Control of $T_c$</td>
<td>Difficult to control by film thickness</td>
<td>Composition control $T_c$; Cu$<em>{25}$Te$</em>{75}$ (At. %) $- T_c = 58$ mK</td>
<td>Enabling feature in amorphous alloys</td>
</tr>
<tr>
<td>Intrinsic noise: 1/f, thermal fluctuations &amp; Johnson noise</td>
<td>Quasiparticles scattered by grain boundaries, crystal defects</td>
<td>Quasiparticles in superconducting metallic thin-films are not scattered from grain boundaries or other crystal defects below $T_c$</td>
<td>Noise will be near fundamental limit</td>
</tr>
<tr>
<td>Excess NEP</td>
<td>Source unknown: 2X-10X larger than theoretical expectation</td>
<td>In glassy metal films, noise levels are reduced by homogeneity of single layer film</td>
<td>Large reductions possible</td>
</tr>
<tr>
<td>Device Fabrication</td>
<td>Design difficult to synthesize for very thin films</td>
<td>Single layer thin film thermistor easily fabricated, lead structures can be made from same alloy system; w/higher $T_c$</td>
<td>Enabling features</td>
</tr>
</tbody>
</table>

Basic MGTES Architecture

To illustrate the design advantages of MGTES detectors in accordance with embodiments of the invention, the application of the MGTES detectors as x-ray radiation and infrared radiation (IR) detectors is described herein. For IR sensing, the device design would be very similar, except without departing from the scope of the present invention.

An MGTES element can be fabricated as a 140 µm x 140 µm sized device, on a Low-Stress-Silicon-Nitride (LSN) substrate of varying thickness (0.25 µm < $t_{LSN}$ < 1 µm). To tune the thermal conductance $G$, membrane-isolated TES designs are used, wherein the superconducting film is deposited onto a thin Silicon-Nitride (Si–N) membrane, which is thermally isolated by thin Si–N support beams of low thermal conductance. The MGTES design has an advantage in that its superconducting leads can be deposited using higher transition temperature compositions from the same alloy system as the TES element itself.

Shown in FIG. 3 is the SQUID current readout, whose output is used in feedback to the bias voltage to maintain the operating point. FIG. 3 illustrates a schematic of a MGTES detector architecture in accordance with one or more embodiments of the invention.

Superconducting metallic glass transition-edge sensors (MGTES) can be fabricated using a single-layer glassy (amorphous) superconductive thin film as the active device element, which is overall a much simpler device architecture compared to the SOA multilayer TES designs. The simplified architecture greatly increases the ability to fabricate large arrays of MGTES detectors, with minimal variation in $T_c$, from one element to another. MGTES films may be deposited onto substrates held at or near room temperature, which greatly improves device yield compared to the SOA proximity effect TES devices, where the substrate temperatures are raised to 600-700°C. During the deposition process, MGTES films deposited onto substrates held between 77-300 K would exhibit very uniform amorphous structures for good glass forming alloys.

TABLE 1

<table>
<thead>
<tr>
<th>MGTES vs. State-of-the-Art.</th>
<th>Improvement</th>
</tr>
</thead>
<tbody>
<tr>
<td>TES Current SOA (bilayer)</td>
<td>MGTES (Superconducting amorphous metal thin film)</td>
</tr>
<tr>
<td>TES Figure of Merit</td>
<td>MGTES (Superconducting amorphous metal thin film)</td>
</tr>
<tr>
<td>Control of $T_c$</td>
<td>Difficult to control by film thickness</td>
</tr>
<tr>
<td>Intrinsic noise: 1/f, thermal fluctuations &amp; Johnson noise</td>
<td>Quasiparticles scattered by grain boundaries, crystal defects</td>
</tr>
<tr>
<td>Excess NEP</td>
<td>Source unknown: 2X-10X larger than theoretical expectation</td>
</tr>
<tr>
<td>Device Fabrication</td>
<td>Design difficult to synthesize for very thin films</td>
</tr>
</tbody>
</table>

The energy resolution limit of the TES device (including Johnson noise in the film and the thermodynamic fluctuations between the detector and the heat bath) is given by reference [1]:

$$\Delta E_{\text{res}} = \sqrt{\hbar g T C(1/\alpha)\sqrt{\kappa}}$$

Eqn. 1

where $C$ is the total heat capacity of the superconducting thin film and absorber. The factor $n = d \log P / d \log T$ is the logarithmic derivative of the bias power with respect to temperature, typically, $n = 3-5$. In Eqn. 1, $\alpha$ is the logarithmic sensitivity factor

$$\alpha = \frac{d \log R}{d \log T} = \left( \frac{R}{\frac{dT}{dR}} \right)$$

Eqn. 2

The $\alpha$ value in SOA TES devices based on polycrystalline films is typically 20 < $\alpha$ < 200. The $\alpha$ value is a measure of the sharpness of the superconducting transition, and it is strongly

The text continues with detailed descriptions and explanations of the technical aspects of the MGTES technology, including fabrication processes, material properties, and device performance metrics.
dependent on the properties and the state of the film. The \( \alpha \) values in SOA TES devices are reduced, manifest by the complexity of the elemental metallic bilayer design, which results in a broadened transition widths of the order \( \Delta T_c \approx 2-30 \) mK.

The MGTEs may exhibit a significantly improved energy resolution, because amorphous superconducting films can be fabricated with very narrow transition widths, as low as \( \Delta T_c \approx 100 \) µK. Further, such transition widths may only be limited by intrinsic superconducting fluctuations. Due to the findings presented in numerous studies, it is accepted that for amorphous superconductors, the contribution to the transition width \( \Delta T_c \) from superconducting fluctuations is well described using the Aslamazov-Larkin (AL) theory. As a means of estimating the performance of MGTEs devices, the contribution to the transition width \( \Delta T_c \) may be calculated using the Aslamazov-Larkin (AL) theory for superconducting fluctuations (see [10]). AL fluctuations contribute to broadening of the transition width, and are dominant near the lower end of the transition, i.e., near the zero resistance.

\[ \Delta T_c = 0.5 \times 10^{-5} \rho(T) \]  
Eqn. 3

The resistance per square \( R_{\parallel}(\Omega) \) was calculated from data presented in Ref. [11] by using its definition:

\[ R_{\parallel}(\Omega) = \frac{\rho}{l} \]  
Eqn. 4

where \( \rho \) is the film resistivity in \( \Omega \cdot \text{m} \), and \( t \) is the film thickness in meters. Narrow superconducting transition widths \( \Delta T_c \), predicted by Eqn. 3 & 4 above are somewhat universal to superconducting amorphous thin films. FIG. 4 shows the superconducting transition observed in an amorphous Zr\(_{75}\)Rh\(_{25}\) (At. %) splat-quenched foil (e.g., of Ref. [7]) in accordance with one or more embodiments of the invention. The Zr—Rh and Zr—Cu alloys are model systems, and therefore are relevant for a discussion of the magnitude of superconductive fluctuations near \( T_c \).

To estimate the performance of an MGTEs device fabricated from amorphous Zr\(_{75}\)Rh\(_{25}\) and Zr\(_{60}\)Cu\(_{40}\) films, the AL theory is applied to calculate the superconducting transition width \( \Delta T_c \). The results of these estimates are provided in Table 2.

<table>
<thead>
<tr>
<th>Alloy Composition</th>
<th>Tc (K)</th>
<th>Rc (Ω)</th>
<th>Calculated</th>
<th>Calculated</th>
</tr>
</thead>
<tbody>
<tr>
<td>Zr(<em>{75})Rh(</em>{25})</td>
<td>1000</td>
<td>4.56</td>
<td>22.0</td>
<td>1.53e-3</td>
</tr>
<tr>
<td>Zr(<em>{60})Cu(</em>{40})</td>
<td>163e-8</td>
<td>0.3</td>
<td>16.3</td>
<td>0.24e-3</td>
</tr>
</tbody>
</table>

In Table 2, the Aslamazov-Larkin theory is applied to calculate the transition width \( \Delta T_c \), and the calculated logarithmic sensitivity factor \( \alpha \) in Zr\(_{75}\)Rh\(_{25}\) and Zr\(_{60}\)Cu\(_{40}\) films.

As described above, narrow transition widths \( \Delta T_c \) are somewhat universal to superconducting amorphous thin films. The electron transport and superconductive properties of amorphous metals are reported in reviews by Mizutani, Howson & Gallagher, and Naugle (see [20]-[22]). Reports of superconducting behavior at low temperatures, \( T_c < 1 \) K, in two alloy systems: Cu\(_{50}\)Ti\(_{50}\) (\( T_c < 58 \) mK) and Cu\(_{50}\)Zr\(_{50}\) (\( T_c < 320 \) mK) are useful. Based upon such alloys, a number of alloy compositions, with ternary additions, may exhibit \( T_c \)'s in the range \( T_c = 65-75 \) mK.

The alloys in both of these systems are strongly scattering metallic glasses (i.e., amorphous metals), where the conductance is due to the d-band conduction. Such alloys exhibit a negative temperature coefficient of resistivity \( \alpha < 0 \), with resistivity values that are well above the Mooij correlation limit \( \rho > 150 \) µΩ-cm (see [12]). For alloys with resistivities above this limit, the temperature dependence, \( \rho(T) \), is small and can be tuned via composition.

Using the calculated superconductive transition width, the logarithmic sensitivity factor \( \alpha \) can also be estimated (and is included in Table 2 above):

\[ \sigma = \frac{d \log R(T)}{dT} \approx \frac{T_c}{R} \frac{d \log R(T)}{dT_c} \]  
Eqn. 5

The predicted superconductive transition widths are \( \Delta T_c \approx 1.53 \) mK and \( \Delta T_c \approx 0.24 \) mK, for Zr\(_{75}\)Rh\(_{25}\) and Zr\(_{60}\)Cu\(_{40}\), respectively. \( \Delta T_c \)'s of this magnitude provide large logarithmic sensitivity factors, and the calculated results are promising.

The estimated AL fluctuation spectrum contribution to \( \Delta T_c \approx 1.53 \) mK for Zr\(_{75}\)Rh\(_{25}\) is especially promising: 1) for the qualitative agreement with the experimentally determined \( \Delta T_c \approx 7 \) mK value for a 45 µm thick foil; and 2) the large \( T_c \), which suggests the fabrication of MGTEs arrays operating at higher temperatures. Temperatures in this range, \(-4 \) K, are commercially viable for medical imaging applications.

The calculated logarithmic sensitivity factors are much greater than the known values for the SOA proximity effect bilayer TES devices. In calculating a for the amorphous superconductors, it may be assumed that \( \Delta R/R = 1 \). This is reasonable for low bias points on the Zr\(_{75}\)Rh\(_{25}\) and Zr\(_{60}\)Cu\(_{40}\) transition curves. These alloys are strongly scattering metallic glass, where the conduction is due to the d-band conduction (see [11]). This alloy exhibits a negative temperature coefficient of resistivity \( \alpha < 0 \), with resistivity values well above the Mooij correlation limit \( \rho > 150 \) µΩ-cm (see [12]). For alloys with resistivities above this limit, the temperature dependence, \( \rho(T) \), is small and can be tuned via composition.

The temperature dependence of resistivity curves for: A) crystalline metals, B) weakly-scattering metallic glasses, and C) strongly-scattering metallic glasses, are shown in FIG. 5 in accordance with one or more embodiments of the invention. In other words, FIG. 5 illustrates the schematic temperature dependence of the electrical resistivity, \( \rho_e \), for: A) crystalline metals, B) weakly-scattering metallic glasses, and C) strongly-scattering metallic glasses. In the strongly scattering alloys of the type C, at low temperatures quantum corrections to the temperature dependence of resistivity become important in the weak-localization regime (WLR). In the WLR, the electron propagation between scattering events is no longer classical as there is significant interference between scattered partial waves. There are two sources of correction: (a) the ‘localization’ effect, which considers the quantum interference effects and (b) the ‘interaction’ effect, which considers the modification of the \( e^{-e} \) interaction in the WLR. These ideas have been very successful in describing the behavior in various examples of disordered metals and they represent a fundamental difference between the transport properties of highly resistive metals and metals for which \( \rho < 100 \) µΩ-cm. In amorphous metals, the disordered structure is the primary electron scattering mechanism, so impurities and defects have little effect on the properties. Therefore, the Residual-Resistance-Ratio (RRR) = R(300 K)/R(4.2 K) for an MGTEs device (in accordance with embodiments of the invention) may be of the order RRR = 1. Such an embodiment reduces the effects of film non-uniformities, providing narrow transitions.

### Table 2

<table>
<thead>
<tr>
<th>Alloy Composition</th>
<th>Tc (K)</th>
<th>Rc (Ω)</th>
<th>Calculated</th>
<th>Calculated</th>
</tr>
</thead>
<tbody>
<tr>
<td>Zr(<em>{75})Rh(</em>{25})</td>
<td>1000</td>
<td>4.56</td>
<td>22.0</td>
<td>1.53e-3</td>
</tr>
<tr>
<td>Zr(<em>{60})Cu(</em>{40})</td>
<td>163e-8</td>
<td>0.3</td>
<td>16.3</td>
<td>0.24e-3</td>
</tr>
</tbody>
</table>
Amorphous superconductors have no long-range order, and so they show no anisotropy effects, Brillouin-zone effects or precipitation effects. Obviously, they also lack crystal interfaces (grain boundaries) and crystalline imperfections (dislocations, twins, stacking faults, and interstitial impurities). These properties have made superconducting metallic glasses popular for testing theories of transition widths, e.g., Nagaie et al’s results that agree well with the AL theory (see [13]-[14]) Thus, the use of the AL theory to predict ΔTc’s is reasonable. Further, there is evidence of 2D effects in thin Cu—Ti films that may be examined.

In high-quality MGTES thin films held under low-bias and low-1, smaller ΔT can be realized; with logarithmic sensitivity scaling as α=ΔT ΔTc−1 and values approaching α~10000 possible. The impact of a larger logarithmic sensitivity α is immediate. The resolution of TES devices is given by Eqn. 1, shown again below (see ref. [3]).

\[ \Delta E_{FWHM} = \sqrt{\frac{k_B T_0^2 (1/\alpha) \sqrt{\pi}}{2}} \]  

Compared to the SOA TES with 50<α<200, the resolution of embodiments of the invention may be improved by factors proportional to 1/α2, which could yield reductions of up to 250% in ΔE_{FWHM}.

Similarly, MGTES device embodiments may exhibit near-theoretical noise-equivalent-power (NEP) values. This performance improvement may arise from the intrinsic factors described above, and also extrinsic factors. For example, thin metallic glass films tend to grow with very little residual stress compared to polycrystalline metal films (where the stresses can be quite large) (see [15]). The work by R. R. Hake further summarizes the universal trend of narrow ΔTc’s for metallic glasses, in almost bulk form, i.e., in melt-spun ribbon form (see [16]) which reports work for binary transition-metal alloys based on zirconium (Zr). Of particular note is a Zr₅₀Cu₃₀ (At. %) specimen with Tc=2.10 K, and ΔTc=4 mK; which yields ΔTc/ΔTc=1.91×10⁻³.

In addition to the above, embodiments of the invention may utilize two early-transition-metal/late-transition-metal (ETM/LTM) alloy systems known to exhibit superconducting behavior below 1 K: 1) amorphous Cu₃₅Ti₆₅ (At. %), which has Tc~58 mK; and 2) amorphous Cu₆₀Zr₄₀ may be used. Embodiments of the invention may use these alloy and near-neighbor compositions in the respective alloy systems (see refs. [18] and [19]).

Performance metrics for the base amorphous metal systems that may also be examined, i.e., Cu₁₋ₓTiₓ and Cu₁₋ₓZrₓ (At. %), are shown in Table 3 (see refs. [18] and [19]):

<table>
<thead>
<tr>
<th>Alloy</th>
<th>Tc (K)</th>
<th>ρ (Ω-cm) × 10⁻⁶</th>
</tr>
</thead>
<tbody>
<tr>
<td>Cu₃₅Ti₆₅</td>
<td>0.058</td>
<td></td>
</tr>
<tr>
<td>Cu₆₀Ti₄₀</td>
<td></td>
<td>230</td>
</tr>
<tr>
<td>Cu₆₀Zr₄₀</td>
<td>0.32</td>
<td>183</td>
</tr>
</tbody>
</table>

To estimate the performance of an MGTES device fabricated from an amorphous CuₓZr₁₀₀ film, the AL theory can be applied to calculate the superconducting transition width ΔTc. This information is provided in Table 4.

<table>
<thead>
<tr>
<th>Cu-content (At. %)</th>
<th>Transition width in Cu₆₀Zr₄₀</th>
<th>Calculated ΔTc (K)</th>
</tr>
</thead>
<tbody>
<tr>
<td>60</td>
<td>183e-8</td>
<td>920</td>
</tr>
<tr>
<td></td>
<td>0.3</td>
<td>19.89</td>
</tr>
<tr>
<td></td>
<td>90.7e-6</td>
<td></td>
</tr>
</tbody>
</table>

The predicted superconductive transition width is ΔTc~0.7 µK. In MGTES device embodiments, ΔTc’s of this magnitude may provide large logarithmic sensitivity factors. This ΔTc value yields the following conservative estimate for the logarithmic sensitivity factor α,

\[ \alpha = \frac{\Delta R}{R} \approx \frac{\Delta T}{T} \approx \frac{\Delta T}{Tc} \approx 3333 \]

This number is much greater than the value for the SOA proximity effect TES device. In calculating α, ΔR/R=1 is assumed. It may be recognized that an α of this magnitude is not realized when biasing a TES device in the ETF mode but, one can expect that the large value intrinsic to superconducting amorphous films may enable lower biasing points or a reduced noise equivalent power value.

Accordingly, embodiments of the invention may synthesize single-layer superconducting amorphous alloy films from the new class of multicomponent bulk metallic glass forming alloys, which exhibit a greater resistance to crystallization, and a higher glass-forming-ability (GFA). There are a number of reports of superconductive behavior for these alloys at temperatures below 1 K. Therefore, ternary, quaternary, and higher order alloying additions may be added to the binary alloys to tune the Tc value and examine the effect of alloying on the MGTES device performance.

In view of the above, the single-layer superconducting amorphous metal alloy used in embodiments of the invention may consist of an early-transition-metal/late-transition-metal (ETM/LTM) alloy system that exhibits superconductive behavior. The early transition metal (ETM) elements may be drawn from elements in Groups IVB, VB, and VIIB of the periodic table, and the late-transition (LTM) metal elements may be drawn from elements in groups VIIIIB, IB, and IB of the periodic table. Such alloys may be deposited onto a substrate using sputtering, atomic-layer-deposition, electron-beam evaporation, or thermal evaporation.

**MGTE Architecture for X-Ray and IR Radiation Detection**

As an efficient X-ray absorber, a modified laminated high fill-fraction array of Bi absorber structures may be employed, similar to that employed by Chervenak et al (e.g., the laminate Bi/Cu absorbers) (see ref. [17]). This absorber consists of 8 total alternating individual Bi/Cu films, with layer thicknesses of 8.5 and 0.8 µm, respectively. This mushroom-type absorber structure is shown in Fig. 6 in accordance with one or more embodiments of the invention.

However, to improve the x-ray efficiency, a more efficient design may be adopted (e.g., a reduced Bi-thickness to increase intra-layer x-ray photon thermalization, coupled with an Au-interlayer instead of Cu). The electronic heat constant γe for Cu and Au are similar, 0.695 and 0.729 mJ/mol-K², respectively. The higher Z of Au will improve the x-ray quantum efficiency. Measurements will be conducted to establish the heat capacity C. Depending on the superconducting metallic glass alloy used, MGTES device embodiments may utilize a self-absorbing MGTES superconducting thermistor element, using alloys selected from the Mo—Re,
Pulse-tube-refrigerator (PTR) systems that are commercially available provide a continuous adiabatic demagnetization refrigerator (ADR) system as the superconducting amorphous metal alloys used as the thermistor element. For example, the superconducting leads may be made using Zr$_{76}$Cu$_{24}$ (At. %) with $T_c$=3.5 K; and the MGTES element (Thermistor) may be made using Zr$_{40}$Cu$_{60}$ (At. %) with $T_c$=0.32 K.

MGTES Device Exemplary Embodiments

MGTES detectors may be designed for measurements conducted on a platform that operates at low temperatures (~50 mK). Each MGTES device may be run in the deep Electrothermal Feedback (ETF) mode, and the noise characteristics of our sensors may be tested as described by Irwin et al. [1]-[3]. Depending on the alloy system under investigation and characteristics of the amorphous metals prepared, the noise performance on thermally isolated island structures or small volume isolation architectures may be investigated. Examples of both structure types are shown in FIG. 7 and FIG. 8. In this regard, FIG. 7 illustrates four TES sensors on a SiN thermally isolated island structure in accordance with one or more embodiments of the invention. FIG. 8 illustrates distributed antenna-coupled small-volume e arrays in accordance with one or more embodiments of the invention. The left side of FIG. 8 illustrates a meandering aluminum structure (G) that forms an array of slot antennas. The two sides can be connected periodically with an array of MGTES microbolometers (B), each with a normal state resistance of tens of ohms (see ref [10]).

Conclusion

This concludes the description of the preferred embodiment of the invention. The following describes some alternative embodiments for accomplishing the present invention.

In view of the above, alloys used in MGTES device embodiments have significantly higher superconducting transition temperatures than the SOA TES devices based on thin films of Ti ($T_c$~0.5 K), or multi-layer Mo/Au designs that exploit the superconducting proximity effect ($T_c$~0.1 K). The complicated SOA TES device design requires a complex fabrication process; making it difficult to produce large arrays with uniform performance. The unexplained excess noise equivalent power (NEP) spectrum values observed in SOA TES systems (noise excess about 10% over theoretical expectations) will be reduced in MGTES systems due to: 1) the simpler device design (single thin film); 2) the intrinsically high electrical resistivity (yields RRR ~1); and 3) the intrinsically narrow superconducting transition region in superconducting metallic glasses, $\Delta T_c$, which provides an increased energy resolution, provided by correspondingly larger logarithmic sensitivity factors $\alpha$=$\log R(T)/\log T_c$. Other applications include: 1) x-ray detectors for medical systems; and 2) MGTES microcalorimeters as radioactive $\alpha$-particle or $\gamma$-ray detectors for Nuclear Forensics applications.

In view of the above, the MGTES sensors of embodiments of the invention are a break-through superconducting transition-edge sensor with unprecedented performance. In particular, MGTES sensors may achieve the following improvements over that of the prior art:

- develop superconducting amorphous metal alloys, with tunable $T_c$ for application to MGTES sensors;
- MGTES sensors that take full advantage of the intrinsic fluctuation limits in amorphous superconductors; and
- MGTES array resulting in enhanced energy resolution and reduced noise floor.

The foregoing description of the preferred embodiment of the invention has been presented for the purposes of illustration and description. It is not intended to be exhaustive or to limit the invention to the precise form disclosed. Many modifications and variations are possible in light of the above teaching. It is intended that the scope of the invention be limited not by this detailed description, but rather by the claims appended hereto.

REFERENCES


What is claimed is:

1. A method for fabricating a superconducting metallic glass transition-edge-sensor (MGTES), comprising: depositing a single-layer superconducting amorphous metal alloy on a substrate, wherein the single-layer superconducting amorphous metal alloy is an absorber for the MGTES and is electrically connected to a circuit configured for readout and biasing to sense electromagnetic radiation.

2. The method of claim 1 wherein the substrate comprises a low-stress-silicon-nitride (LSN) substrate of varying thickness.

3. The method of claim 1 wherein the MGTES is deposited onto the substrate held at or near room temperature.

4. The method of claim 1 wherein the MGTES is deposited onto the substrate held between 77-300 K.

5. The method of claim 1 further comprising: tuning a thermal conductance of the MGTES using a membrane-isolation method to support the MGTES.

6. The method of claim 1 further comprising: depositing superconducting leads of the MGTES onto the single-layer superconducting amorphous metal alloy to electrically connect to the circuit, wherein the superconducting leads are comprised of superconducting amorphous metal alloys comprised of a same alloy system as the single-layer superconducting amorphous metal alloy, but with chemical compositions chosen such that the same alloy system exhibits a higher superconducting transition temperature, Tc.

7. The method of claim 1 further comprising: reading out, using the circuit, one or more pixels from the MGTES using superconducting quantum interference (SQUID) amplifiers.

8. The method of claim 7, wherein the biasing uses an output of the SQUID current readout in feedback to apply a bias voltage to the single-layer superconducting amorphous metal alloy to maintain an operating point on a transition curve of the MGTES.

9. The method of claim 1 wherein the MGTES is operated in a temperature range that is achieved using a closed-cycle cryogenic system that uses He.

10. The method of claim 1 further comprising formatting the MGTES into an array having 10⁵ or more pixels.

11. The method of claim 1 further comprising changing a chemical composition of the single-layer superconducting amorphous metal alloy to control a Tc of the MGTES.

12. The method of claim 1, wherein: the single-layer superconducting amorphous metal alloy comprises an early-transition-metal/late-transition-metal (ETM/LTM) alloy system that exhibits superconducting behavior; and the early transition metal (ETM) elements are drawn from elements in Groups IVB, VB, and VIIIB of the periodic table, and the late-transition (LTM) metal elements are drawn from elements in groups VIIIIB, IB, and IIB of the periodic table.

13. The method of claim 1, wherein the depositing comprises: depositing a first metal onto the substrate; and depositing a second metal onto the substrate, wherein the first metal and the second metal are deposited under conditions to obtain the single-layer superconducting amorphous metal alloy using a method of sputtering, atomic-layer-deposition, electron-beam evaporation, or thermal evaporation.

14. The method of claim 1, wherein: the absorber comprises a modified laminated high fill-factor array of Bi absorber structures; the absorber comprises alternating individual Bi/Au films; and a layer thickness of the Bi film increases intra-layer x-ray photon thermalization.

15. A superconducting metallic glass transition-edge sensor (MGTES) comprising: a circuit configured for readout and biasing to sense electromagnetic radiation; and...
an absorber, for the MGTES, that is electronically connected to the circuit, wherein the absorber comprises a single-layer superconducting amorphous metal alloy.

16. The superconducting metallic glass transition-edge sensor of claim 15, wherein a thermal conductance of the MGTES is tuned using a membrane-isolation type method to support the MGTES.

17. The superconducting metallic glass transition-edge sensor of claim 15 further comprising:

superconducting leads that connect the single-layer superconducting amorphous metal alloy to the circuit, wherein the superconducting leads are comprised of a different composition within a same alloy system as the superconducting amorphous metal alloys used as a thermistor element.

18. The superconducting metallic glass transition-edge sensor of claim 15, further comprising:

a superconducting quantum interference (SQUID) amplifier that is used to read out, using the circuit, one or more pixels from the MGTES.

19. The superconducting metallic glass transition-edge sensor of claim 18, wherein an output of the SQUID current readout in feedback is used to apply a bias voltage to the single-layer superconducting amorphous metal alloy to maintain an operating point on a transition curve of the MGTES.

20. The superconducting metallic glass transition-edge sensor of claim 15 wherein the MGTES is operated in a temperature range that is achieved using a closed-cycle cryogenic system that uses $^4$He, a continuous adiabatic demagnetization refrigerator (ADR with 4-stages), a He$^3$/He$^4$ dilution refrigerator, or a cryogenic cooling system that uses liquid He.

21. The superconducting metallic glass transition-edge sensor of claim 15 wherein the MGTES is formatted into an array having $10^3$ or more pixels.

22. The superconducting metallic glass transition-edge sensor of claim 15 wherein a chemical composition of the single-layer superconducting amorphous metal alloy is changed to control a $T_c$ of the MGTES.

23. The superconducting metallic glass transition-edge sensor of claim 15, wherein:

the single-layer superconducting amorphous metal alloy comprises an early-transition-metal/late-transition (ETM/LTM) metal alloy system that exhibits superconductive behavior; and

the early transition metal (ETM) elements are drawn from elements in Groups IVB, VB, and VIIIB of the periodic table, and the late transition (LTM) metal elements are drawn from elements in Groups VIIIIB, IB, and IIB of the periodic table.